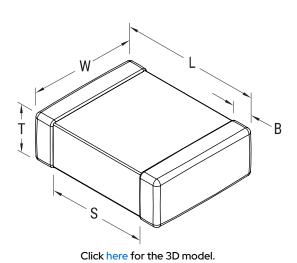




SMD Comm X8G HT150C Flex, Ceramic, 0.068 uF, 5%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	130 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

	Capacitance	0.068 uF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	5%
	Voltage DC	100 VDC
	Dielectric Withstanding Voltage	250 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
ape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee

Time is 1000 Hours

14.7059 GOhms

**Specifications** 

Insulation Resistance

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

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